502685792 02/19/2014

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2732397

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YI ZHANG	01/22/2014
SITARAMANJANEYULU KANAMARLAPUDI	01/23/2014
LIANGCHI HSU	01/22/2014

RECEIVING PARTY DATA

Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14079165

CORRESPONDENCE DATA

Fax Number:

Phone: (949) 681-8161

Email: qualcomm-pto@lozaip.com

Correspondence will be sent via US Mail when the email attempt is unsuccessful.

Correspondent Name: LOZA & LOZA, LLP/QUALCOMM
Address Line 1: 305 N. SECOND AVE., #127
Address Line 4: UPLAND, CALIFORNIA 91786

ATTORNEY DOCKET NUMBER:	QCOM-2356US (132655)	
NAME OF SUBMITTER:	DEREK YEUNG	
Signature:	/Derek Yeung/	
Date:	02/19/2014 PATENT	

502685792 REEL: 032243 FRAME: 0841

Total Attachments: 5

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ASSIGNMENT

WHEREAS, WE,

- 1. Yi Zhang, a citizen of the The United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714 and a resident of San Diego, California,
- 2. Sitaramanjaneyulu Kanamarlapudi, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714 and a resident of San Diego, California,
- 3. Liangchi Hsu, a citizen of the The United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714 and a resident of San Diego, California

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to ENHANCED RECONFIGURATION PROCEDURE AT A MOBILE TERMINAL TO REDUCE SIGNALING AND POWER CONSUMPTION OVERHEAD (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No. 14/079,165 filed November 13, 2013, Qualcomm Reference No. 132655, and all provisional applications relating thereto, together with U.S. Provisional Application No. 61/812,821, filed April 17, 2013, Qualcomm Reference No. 132655P1, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States:

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE,

its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

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AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at \geq	an Diego	_, on _	01/22/2014	Harry M
-	LOCATION		DATE	Yi Zhang
Done at	LOCATION	on	DATE	Sitaramanjaneyulu Kanamarlapudi
Done at _	LOCATION	_, on _	DATE	Liangchi Hsu
	200711011			

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at	, on		
-	LOCATION	DATE	Yi Zhang
Done at _	CANDIEGO, on _	01/2-3/14 DATE	Sitaramanjaneyulu Kanamariagudi
Done at _	, on _	DATE	Lianochi Hen

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QUALCOMM Ref. No. 132655
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AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at	, Ó	1	
	LOCATION	DATE	Yi Zhang
Done at	. 0	3	
Done at_	LOCATION	DATE	Sitaramanjaneyulu Kanamarlapudi
Cone at _	Dan Viego, CA, or LOCATION	n <u>Jan 22, 2014</u> DATE	Liangchi Hsu

PATENT REEL: 032243 FRAME: 0847

RECORDED: 02/19/2014